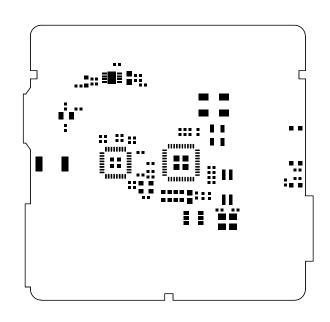
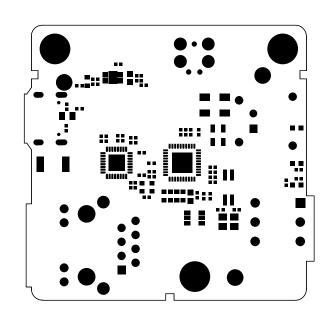


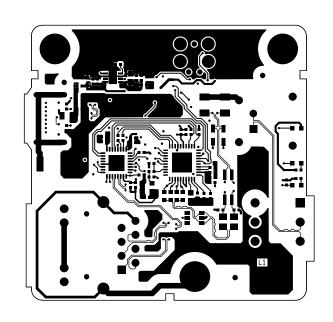
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DESIGNED AT: eInfochips		
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FILM LAYER: SILKSCREEN TOP		



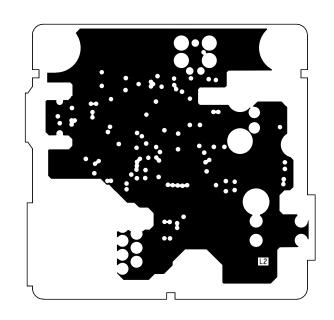
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CARD REF: el_AIT1L_Media_Converter			REV:3.0
FILM LAYER: SOLDER PASTE TOP			



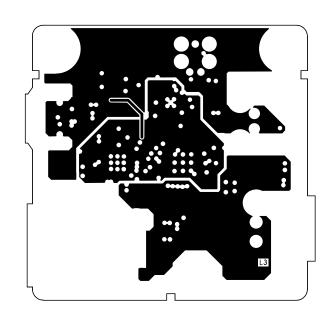
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DESIGNED AT: eInfochips			
CARD REF: el_AIT1L_Media_Converter			REV:3.0
FILM LAYER: SOLDER MASK TOP			



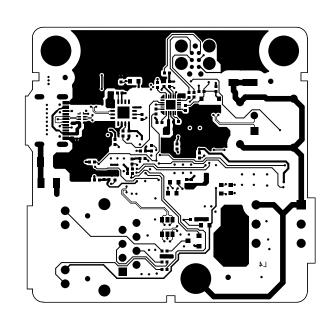
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CARD REF: el_AIT1L_Media_Converter			REV:3.	0
FILM LAYER: L1_TOP LAYER				



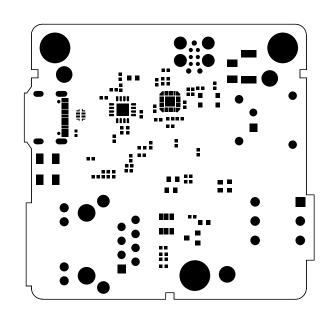
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CARD REF: el_AIT1L_Media_Converter			REV:3.0)
FILM LAYER: L2 GND PLANE				



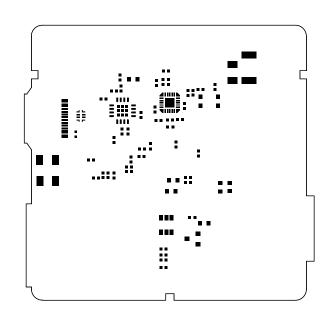
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CARD REF: el_AIT1L_Media_Converter			REV:3.0)
FILM LAYER: L3 GND PLANE				



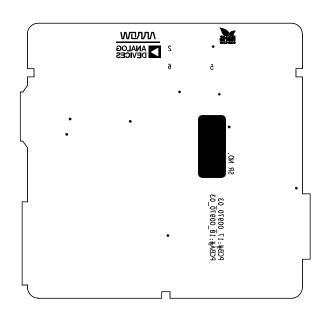
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FILM LAYER: L4 BOTTOM		



eInfochips		·		
DATE: 08_DECEMBER_2021	PCB	NO: 17_	00970_0	03
DESIGNED AT: eInfochips				
CARD REF: el_AIT1L_Media_Converter			REV:3.	0
FILM LAYER: SOLDER MASK BOTTOM				



eInfochips		
DATE: 08_DECEMBER_2021	PCB	NO: 17_00970_03
DESIGNED AT: eInfochips		
CARD REF: el_AIT1L_Media_Converter		REV:3.0
FILM LAYER: SOLDER PASTE BOTTOM		



eInfochips		;		
DATE: 08_DECEMBER_2021	PCB	NO: 17	00970_(03
DESIGNED AT: eInfochips				
CARD REF: el_AIT1L_Media_Converter			REV:3.	0
FILM LAYER: SILKSCREEN BOTTOM				